Squeezing the power out of a Debug and Test Interface (DTI)

IEEE P1149.7, a complementary superset of the IEEE 1149.1 standard

REAL WORLD SIGNAL PROCESSING<sup>™</sup>

TEXAS INSTRUMENTS

# P1149.7 An introduction to the proposed standard

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# **Presentation Outline**

- P1149.7 history and status
- Why 1149.7?
- What can it do?
- What about performance?
- How does it work?
- How is it deployed?



#### 1149.1 and P1149.7

#### What is their relationship?

P1149.7 is *not* a replacement for 1149.1
P1149.7 uses 1149.1 as its foundation
P1149.7 provides 1149.1 extensions
P1149.7 provides 2-pin operating modes



### P1149.7 History and Status

#### MIPI Origins

- $\rightarrow$  Objective define a backwards compatible minimum pin debug interface
- → Strategy requirements gathering, technical debate
- $\rightarrow$  Tactics solicit competing proposals, choose a winner
- → Result P1149.7 was handily selected as winning proposal vs. SWD

#### Collaboration with Nexus consortium

- $\rightarrow$  Objective Compare common needs, explore common solution
- $\rightarrow$  Strategy Joint meetings, compare requirements
- $\rightarrow$  Tactics Specifications reviewed, incorporate feedback
- → Result Agreement to pursue IEEE standard because of large field of use

#### IEEE PAR approved

- $\rightarrow$  Test, Debug, and backwards IEEE 1149.1 compatibility considerations
- $\rightarrow$  Specification reviewed and revision underway
- → Presumed Result IEEE 1149.7 standard in early 2007



#### Why P1149.7?

#### Harness 1149.1 entropy and provide a framework for creativity

- Addresses multiple on-chip TAP controllers
- Serves both applications debug and test needs
- More functions supporting applications debug
- Applications instrumentation over the same pins used for test



### P1149.7 Activity



 $\rightarrow$  MIPI

→ Nexus

 $\rightarrow \text{OCP}$ 

#### Engage Strategic Companies

 $\rightarrow$ Silicon, Tools and Test:

- North America Intel, Freescale, Xilinx, Corelis, EWA, etc.
- Europe STM, Philips, Nokia, Lauterbach, etc.
- Asia NEC, Fujitsu, Toshiba, Sophia, YDC, etc.



→IEEE 1149.7



### **Standards Focus**

#### 1149.1 vs. P1149.7

|      | 1149.1  | P1149.7   |
|------|---|---|
| Test | Boundary Scan:<br>Finding card level<br>connectivity issues | Compliance: Preserving<br>boundary scan for System<br>on a Chip (SoC) |
| Apps |   | Capability: Features for<br>debug                                     |



# Key P1149.7 Objectives

Do more with less

- Operate with fewer pins
- Add instrumentation using the same pins
- TAP power management
- Provide framework for diverse debug technologies
- Preserve gateway to debug of SI errors/defects

Preserve industry investment

- SI IP
- Software IP
- Debug and Test Tools

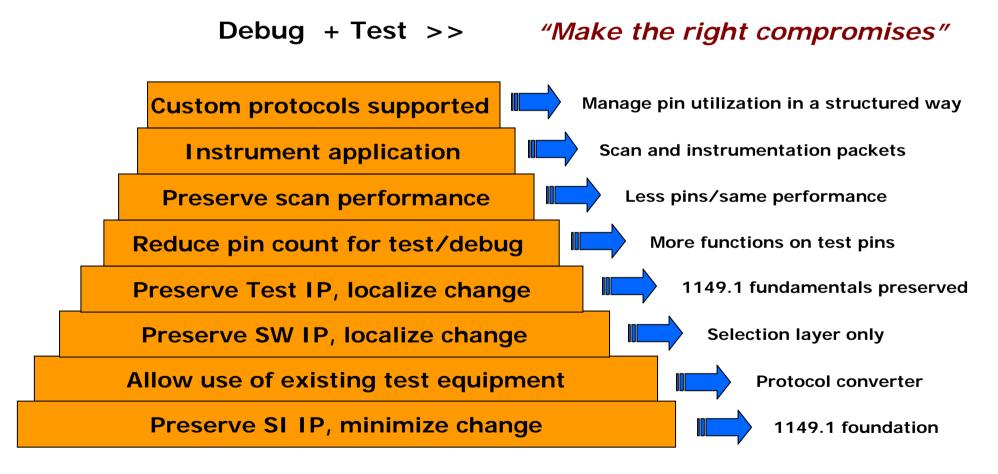
Provide means for innovation/customization

- Pin protocols other than those supporting scan
- Mix and match legacy/new IP
- Equal treatment for all industry IP



### **Applications Debug Forces at Work**

"Hold test gains while achieving better pin utilization"



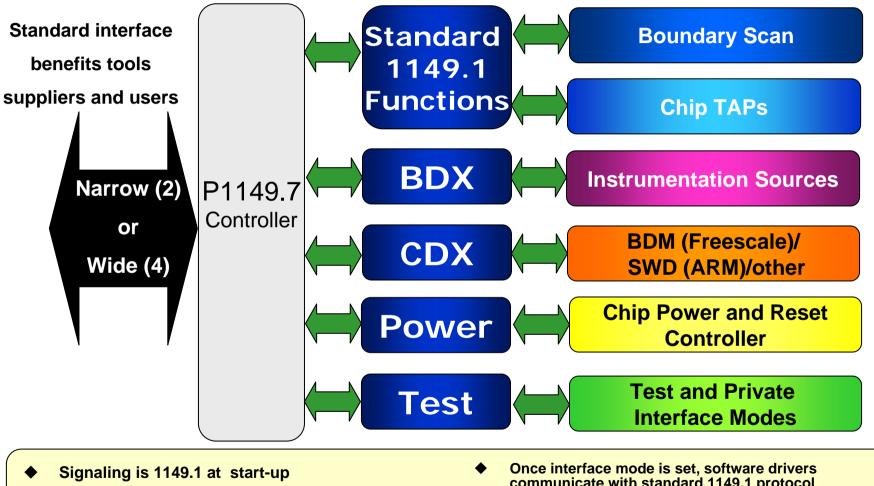


#### So, what can it do?



#### P1149.7 – A Debug and Test Tech. Binder

"All industry IP co-exists behind a standard Interface"

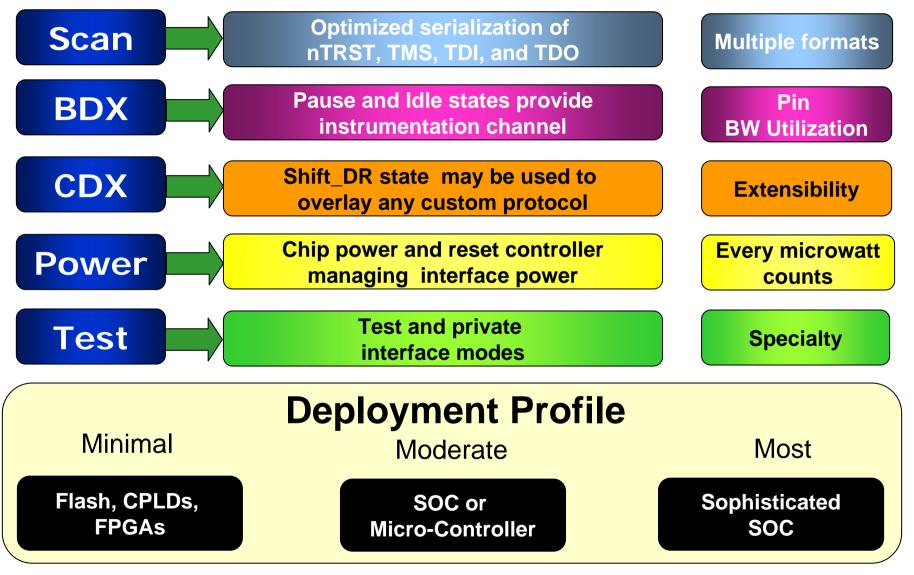


 SW directed mode switches between use of standard and advanced protocol  communicate with standard 1149.1 protocol
 SW controls transmission efficiency by selection of transmission format best suiting system characteristics



### A Look Inside P1149.7

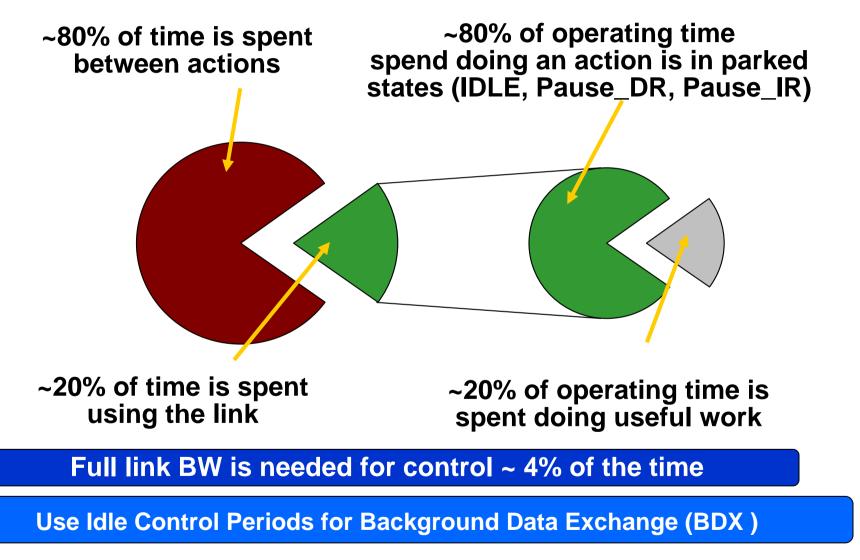
"Major functions"





#### **BDX – Better Use of Link BW**

"The Compound 80/20 Rule of Interface Activity"





# CDX – Custom Use of Link BW

#### "Supports vendor specific protocols"

- Redirects activity during Shift\_DR states
- All controllers do not need to understand protocol
- Only device that is selected for scan participates
- DTS or Device may be master
- Different CDX formats may be TDMed
- Entirely under software control
- Can be invoked "inline" with scans

Full link BW is provide to any function

CDX follows BDX rules set only CDX manages line direction each bit



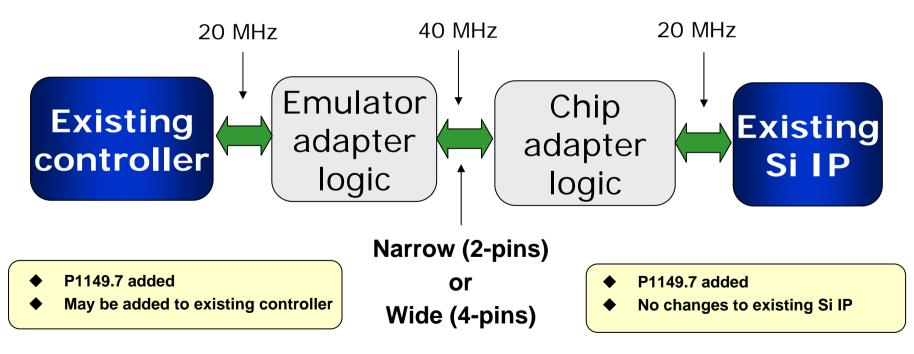
#### So, what about performance?



#### P1149.7 – Adds capability to 1149.1 "Minimizing Changes/Maintaining Performance"

- The same or better than IEEE1149.1 may be achieved in some cases
- With advanced protocol
  - Falling-edge to falling edge timing allows doubling TCK rate
  - The amount of information transferred is minimized to boost performance
  - Two or less bits are transferred/TAP controller state in some cases

#### 2 bits/TAP state/ 2\*TCK rate = the same TCK/TAP state rate as IEEE 1149.1

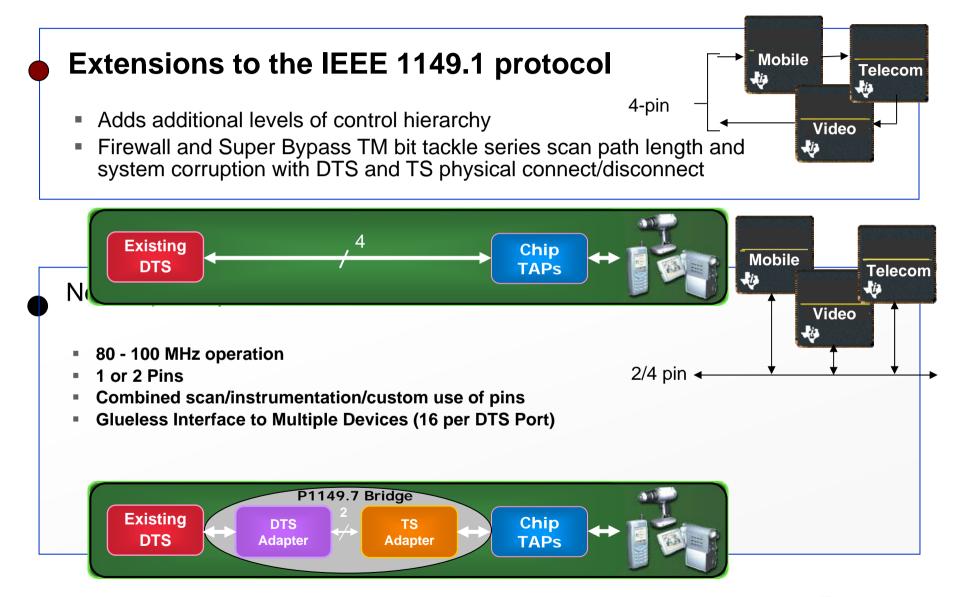




#### So, how does it work?



### P1149.7 Overview

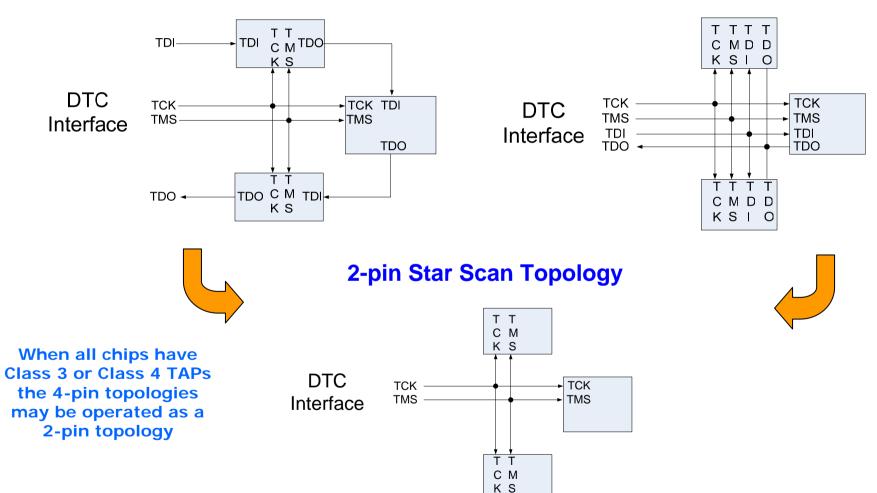




# **Connection Topologies**

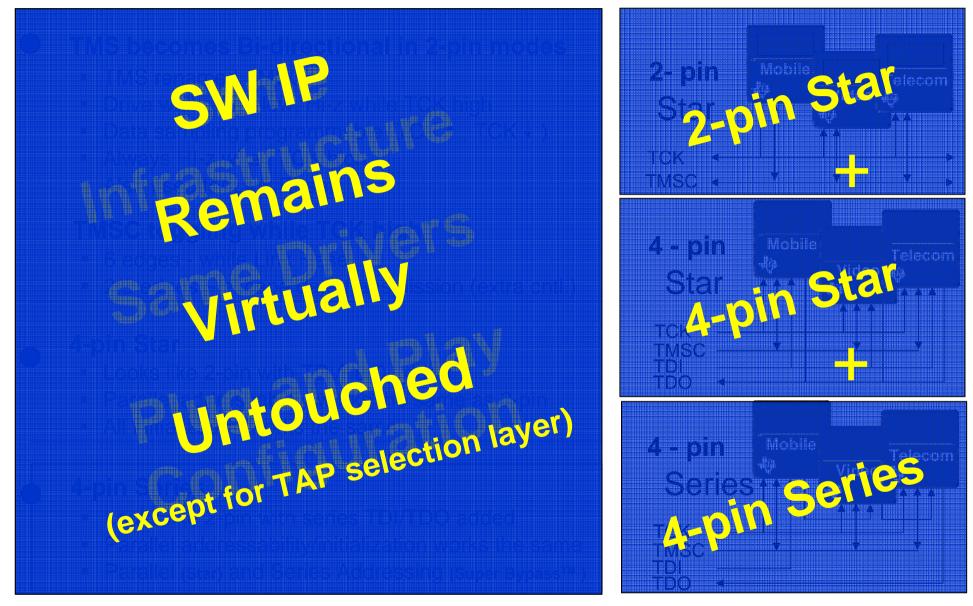
#### 4-pin Series Scan Topology

#### 4-pin Star Scan Topology





### Harmony with the 1149.1 Standard



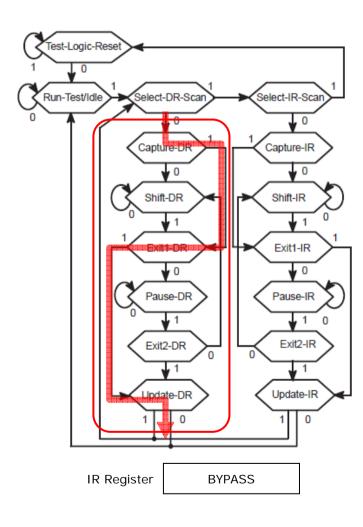


# **Key Control Concepts**

- Extend functionality of BYPASS and IDCODE instructions ("overload" these instructions)
- Keep new command structure invisible to existing 1149.1 TAPs
- Create commands without using TDI or TDO
- Use commands to create registers without changing IR/DR scan paths



### Overloading the Bypass Instruction (using Zero-bit DR-Scans (ZBS))

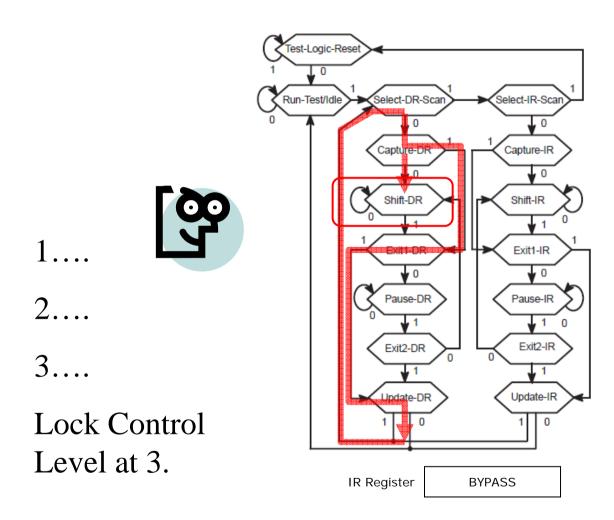


#### Method:

- IR register set to BYPASS or IDCODE instruction by:
  - IR-Scan or
  - Test-Logic-Reset
- ZBS = Capture→Exit→Update
- The number of consecutive ZBSs are counted to create a control level that specifies the overloaded function
- This is performed by standard IEEE 1149.1 TAP controller state sequences



### **Zero-Bit Scans Create Control Levels**



#### Key:

- <u>Count</u> the number of Zero-Bit-Scans (ZBS) to change the definition of BYPASS instruction.
- Lock control level when the Shift-DR state is reached.



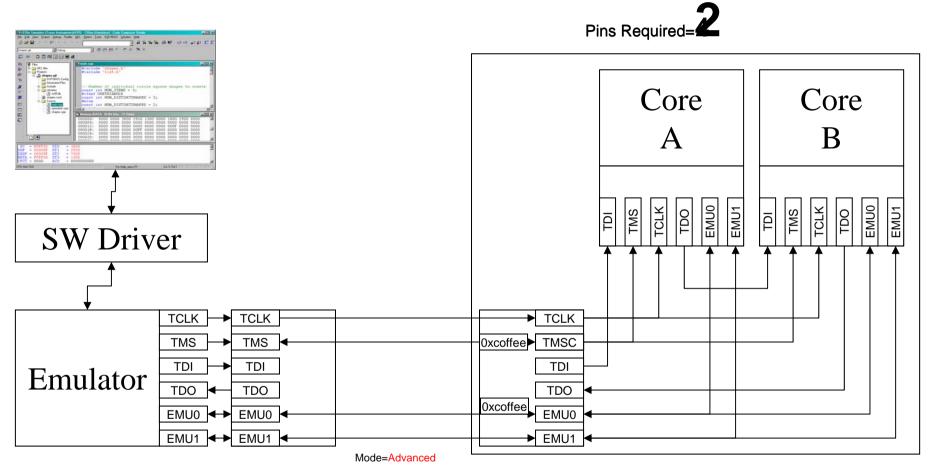
# **Creating a Control Level**

#### ◆ Example: Steps to create a control level 3

1. IR-Scan with BYPASS instr. **BYPASS** instruction 2. 7BS Increment control level from 0 to 1 3. ZBS Increment control level from 1 to 2 4. ZBS Increment control level from 2 to 3 Example: Steps to create a control level 5 1. IR-Scan with BYPASS instr. **BYPASS** instruction 2. ZBS Increment control level from 0 to 1 3. ZBS Increment control level from 1 to 2 4. ZBS Increment control level from 2 to 3 5. ZBS Increment control level from 3 to 4 6. ZBS Increment control level from 4 to 5



# Extending 1149.1



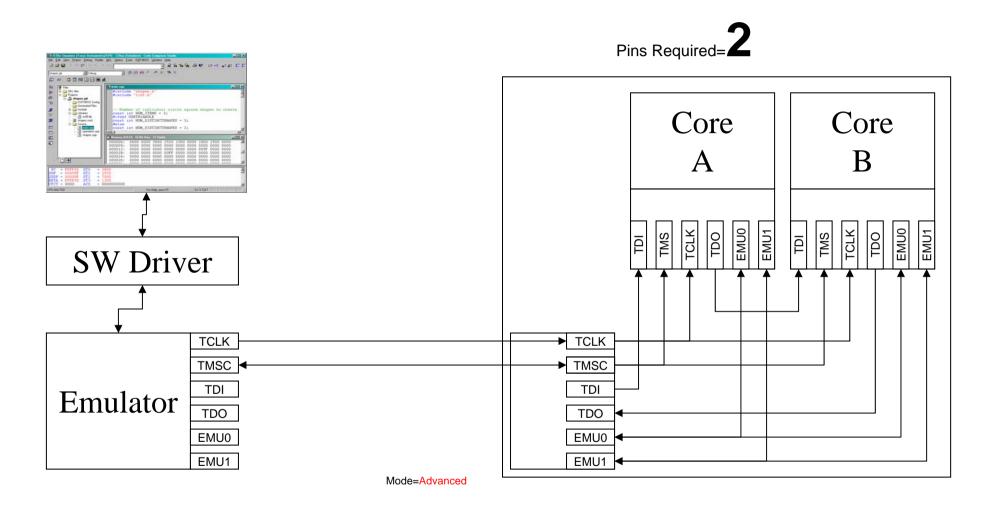
•EMU0 and EMU1 are typically used for to gather large amounts communication with a target application

•Using Background Data eXchange (BDX) and Custom Data eXchange (CDX), target information can be transferred.

•For maximum compatibility, CDX can be used to carry manufacturer defined protocols.



### Extending 1149.1





#### How is it deployed?



#### P1149.7 Deployment Method

#### Capability classes:

3 classes - 4-pin using IEEE 1149.1 protocol 2 classes - 2/4-pin using IEEE 1149.1 protocol



# P1149.7 "Classes"

#### **Deliver:**

a) 1149.1 extensions with standard protocolb) 2-pin operation with advanced protocolc) Bi-modal operation with plug and play

#### With five classes of capability:

- Class T0 IEEE Compliance for chips with multiple TAPs
- Class T1 Add control functions/preserving IP (e.g. chip reset(s))
- Class T2 Add chip selection for series and star configurations
- Class T3 Add two pin operation
- Class T4 Add instruction/custom pin use to two pin operation



# **IEEE P1149.7 Class Details**

| Class <b>TO</b> | • Ensure compliance with 1149.1 to enhance compatibility with industry test infrastructure | <ul> <li>After Test-Logic-Reset (TLR) multi-TAP devices:</li> <li>Conform to mandatory 1149.1 instruction<br/>behavior</li> </ul> |
|-----------------|--|---|
|                 |  |   |
|                 |  | <ul> <li>1-bit DR-Scan for bypass instruction</li> </ul>  |
|                 |  | <ul> <li>Addresses stacked die and multi-chip module needs</li> </ul>   |
| Class T1        | Power: Test logic power-down   | <ul> <li>4 Power Down modes friendly to: Board Test,<br/>Chip Test, and Application Debug</li> </ul>                              |
| Class T2        | Performance:   |   |
|                 | <ul> <li>Shortened multi-chip scan<br/>chains</li> </ul>                                   | Chip Level Bypass   |
|                 | <ul> <li>Glue-less star configuration</li> </ul>   | <ul> <li>Built-in Chip Select Mechanism</li> </ul>  |
| Class T3        | Pins: Less pin and more functions  | <ul> <li>2 pins provide scan, Test-Logic-Reset (TLR), and<br/>instrumentation (serialized transactions)</li> </ul>                |
|                 | •Faster downloads to target  | <ul> <li>Download specific modes (Target Input only)</li> </ul>   |
|                 | •Equivalent performance with fewer pins  | <ul> <li>2x Clock rate and optimized transactions</li> </ul>  |
| Class T4        | Instrumentation  | Concurrent Debug and Instrumentation using  |
|                 |  | same pins   |
|                 |  | <ul> <li>Instrumentation of data passed during Run-Test-<br/>Idle, Pause-DR, and Pause-IR states</li> </ul>                       |
|                 | Customization  | <ul> <li>Custom technologies can use the test access port<br/>pins in Shift-DR state. (ex: SWD, BDM, etc.)</li> </ul>             |

#### Higher numbered classes operate with lower numbered classes



# How will P1149.7 be used?

# Class T0/T1 – any system, mix/match with 1149.1 Class T2

- Series topology Mix/match with 1149.1 devices
- Star topology Match with 1149.7 Class 2

#### Class T3/T4 – (4-pin)

- Series topology Mix/match with 1149.1, T0, T1, and T2 devices
- Series topology Mix/match with T3/T4 devices, operate as 2-pin
- Star topology Mix/match with T2 supporting Star, T3/T4
- Class T3/T4 (2-pin) Mix/match with T3/T4 devices:

1149.1 and 2-pin T3/T4 devices may share either TCK or TMSC but not both if they are used together. The 2-pin and 4-pin interfaces may be also be kept separate.



# **Projected adoption profile**

#### Class 0:

- Should be no barriers
- Class 1:
  - Systems with embedded cores/application dev. needs
  - Some FPGAs
- Class 2 :
  - Systems with large number of chips
  - Systems with embedded cores/application dev. needs

#### Class T3/T4 – (4-pin) :

- Mass market devices that may be mixed with T3/T4 chips in system
- Systems with applications development needs

Class T3/T4 – (2-pin):

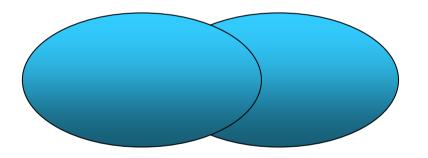
- Wireless handheld devices
- Consumer products

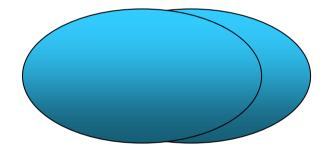


#### Where does P1149.7 take us?

#### Here are the choices >>

1149.1 Test and Debug Overlap 1149.7 Test and Debug Overlap





Test – easier

**Debug - harder** 

Test – a bit slower

**Debug - easier** 

